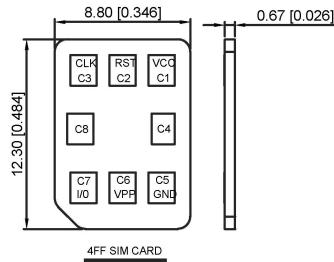
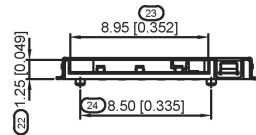


RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

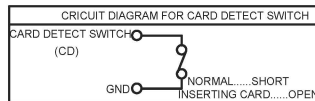


4FF SIM CARD

NOTES:

- MATERIAL:  
HOUSING: HI-TEMP. PLASIC UL 94V-0  
TERMINAL: COPPER ALLOY  
SHELL: SUS
- PLATING:  
TERMINAL:  
CONTACT AREA: AU GOLD FLASH.  
SOLDER AREA: AU GOLD FLASH.  
UNDER PLATE: NICKEL.  
SHELL: NICKEL PLATED OVER ALL.  
SOLDER AREA: GOLD FLASH.
- SPECIALITY:  
3.1 Rated current: 1.0A  
3.2 Rated voltage: 30V  
3.3 Contact Resistance: 50mΩ MAX  
3.4 Insulation Resistance: 1000MΩ MIN 500V DC  
3.5 Dielectric withstanding voltage: 500V AC.  
3.6 Solder ability: 260±0.5°C, 30±10s.  
3.7 Durability: 5000 Cycles Min.  
3.8 Operating condition: Temperature: -40°C ~ +85°C;  
Humidity 80% R.H MAX

▨ PAD  
▩ KEEP OUT AREA



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP. PLASIC UL 94V-0	BLACK

广东星坤科技股份有限公司

生效日期

文件工程章

REVISIONS  
www.xkg.cn www.helloxkb.com www.helloxkb.cn

UNSPECIFIED TOLERANCES

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	SIM CARD CONN
CHKD	DATE	UNIT: mm/in	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.:
			XKNANO-113
		WEIGHT	SHEET
		1.0g	1/1
		REVISION	A0

XKB INDUSTRIAL PRECISION CO., LIMITED

单击下面可查看定价，库存，交付和生命周期等信息

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